



Product data sheet

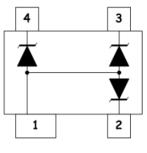
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SP0503BAHTG-MS

Semiconductor Compiance





SOT-143

Features

- Ultra low leakage: nA level
- Operating voltage: 5V
- Low clamping voltage
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 Air discharge: ±15kV
 Contact discharge: ±8kV
 - IEC61000-4-4 (EFT) 40A (5/50ns)
 - IEC61000-4-5 (Lightning) 10A
- RoHS Compliant (8/20µs)

Applications

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)
- Notebook Computers
- SIM Ports
- 10/100 Ethernet

Mechanical Characteristics

- Package: SOT-143
- Lead Finish: Lead Free
- UL Flammability Classification Rating 94V-0
- Quantity Per Reel:3,000pcs
- Reel Size:7inch

Absolute Maximum Ratings(Tamb=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20µs)	Ррр	150	W
ESD per IEC 61000-4-2 (Air)		±15	Ku.
ESD per IEC 61000-4-2 (Contact)	Vesd	±8	Kv
Operating Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	Тѕтј	-55 to +150	°C

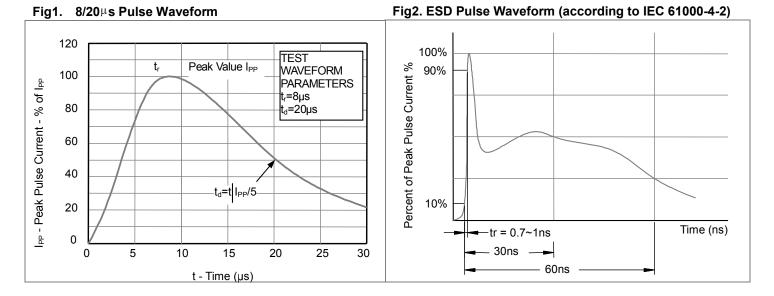




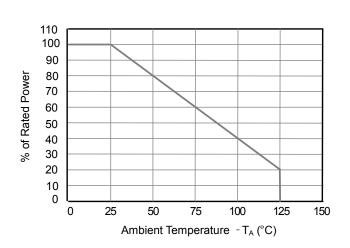
Electrical Characteristics(TA=25°C unless otherwise specified)

P/N	Marking	V _{RWM} (V)	V _{BR} (V)	l⊤ (mA)	Vc @1A	(Max)	(@A)	I µA (Max)	C (Pf) (Typ.)
SP0503BAHTG-MS	503B	5	6	1	10	15	10	1	30

Characteristic Curves





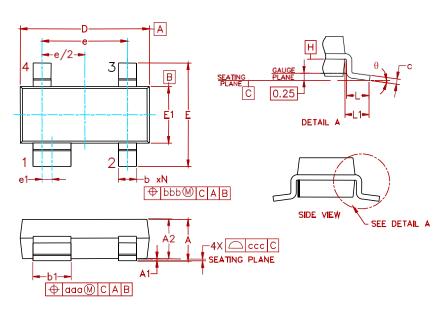






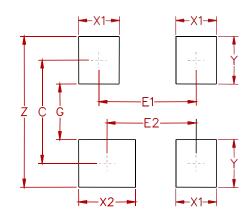
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PACKAGE MECHANICAL DATA



Queen had		Inches		Millimeters			
Symbol	Min.	Nom.	Max.	Min.	Nom.	Max.	
Α	0.031	-	0.048	0.80	-	1.22	
A1	0.000	-	0.008	0.013	-	0.15	
A2	0.020	0.035	0.042	0.75	0.90	1.07	
b	0.011	-	0.020	0.30	-	0.51	
b1	0.029	-	0.037	0.76	-	0.94	
с	0.003	-	0.008	0.08	-	0.20	
D	0.110	0.114	0.120	2.80	2.90	3.04	
Е	0.082	0.093	0.104	2.10	2.37	2.64	
E1	0.047	0.051	0.055	1.20	1.30	1.40	
е	0.075			1.92 BSC			
e1	0.008			0.20 BSC			
L	0.015	0.020	0.024	0.40	0.50	0.60	
L1	(0.021)			(0.54)			
Ν	4			4			
θ	0°	-	8°	0°	-	8°	
aaa	0.006			0.15			
bbb	0.008			0.20			
ссс	0.004			0.10			

Suggested Pad Layout



REEL SPECIFICATION

P/N	PKG	QTY
SP0503BAHTG-MS	SOT-143	3000



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